



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C101FB81PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 100 pF, 50V, ±1%, C0G, 0603

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>101</u> <u>F</u> <u>B</u> <u>8</u> <u>1</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor						
2	Size	0603 (inch code)	L:	1.6	6 ± 0.1 mm	W:	$0.8 \pm$	0.1 mm
3	Dielectric	C0G		8	Inner electrode	1	Ni	
4	Capacitance	100 pF			Termination	(Cu	
(5)	Capacitance	±1 %			Plating	;	Sn 100%	(Pb Free)
	tolerance			9	Product		Automotive)
6	Rated Voltage	50 V		10	Grade code	;	Standard	
7	Thickness	0.8 ± 0.1 mm		11)	Packaging	(Cardboard	Type, 7" reel(4,000ea)

B. Reliability Test and Judgement condition

	Performance	Test condition				
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150°C				
Exposure	Capacitance Change:	Measurement at 24±2hrs after test conclusion				
	within ±2.5% or ±0.25pF whichever is larger					
	Q: 1000 min					
	IR : More than 10,000 $\mathrm{M}\Omega$ or 500 $\mathrm{M}\Omega \! \times \! \mu \! \mathrm{F}$					
	Whichever is Smaller					
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles				
	Capacitance Change:	Measurement at 24±2hrs after test conclusion				
	within ±2.5% or ±0.25pF whichever is larger	1 cycle condition :				
	Q: 1000 min	-55+0/-3℃(15±3min) -> Room Temp(1min.)				
	IR : More than 10,000MΩ or 500MΩ×μF	-> 125+3/-0 °C (15±3min) -> Room Temp(1min.)				
	Whichever is Smaller					
Destructive Physical	No Defects or abnormalities	Per EIA 469				
Analysis						
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle				
	Capacitance Change :	Heat (25~65°C) and humidity (80~98%), Unpowered				
	within ±2.5% or ±0.25pF whichever is larger	measurement at 24±2hrs after test conclusion				
	Q: 350 min					
	IR : More than 10,000 $\mathrm{M}\Omega$ or 500 $\mathrm{M}\Omega \! \times \! \mu \! \mathrm{F}$					
	Whichever is Smaller					
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85°C/85%RH, Rated Voltate and 1.3~1.5V,				
	Capacitance Change :	Add 100kohm resistor				
	within ±2.5% or ±0.25pF whichever is larger	Measurement at 24±2hrs after test conclusion				
	Q: 200 min	The charge/discharge current is less than 50mA.				
	IR: More than 500MΩ or 25MΩ×μF					
	Whichever is Smaller					
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125℃, 200% Rated Voltage,				
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion				
	within ±3.0% or ±0.3pF whichever is larger	The charge/discharge current is less than 50mA.				
	Q: 350 min					
	IR : More than 10,000MΩ or 500MΩ×μF					
	Whichever is Smaller					

	Performance	Test condition				
External Visual No abnormal exterior appearance		Microscope (´10)				
Physical Dimensions	Within the specified dimensions	Using The calipers				
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along				
	Capacitance Change :	3 mutually perpendicular axes of the test specimen (18 shocks)				
	within ±2.5% or ±0.25pF whichever is larger	Peakvalue Duration Wave Velocity				
	Q, IR : initial spec.	1,500G 0.5ms Half sine 4.7m/sec.				
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,				
	Capacitance Change :	Use 8"x5" PCB 0.031" Thick 7 secure points on one long side				
	within ±2.5% or ±0.25pF whichever is larger	and 2 secure points at corners of opposite sides. Parts mounted				
	Q, IR : initial spec.	within 2" from any secure point. Test from 10~2000Hz.				
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5 ℃, 10±1sec.				
Solder Heat	Capacitance Change :					
	within ±2.5% or ±0.25pF whichever is larger					
	Q, IR: initial spec.					
Thermal Shock	Appearance : No abnormal exterior appearance	-55 °C/+125 °C.				
	Capacitance Change :	Note: Number of cycles required-300,				
	within ±2.5% or ±0.25pF whichever is larger	Maximum transfer time-20 sec, Dwell time-15min. Air-Air				
	Q, IR: initial spec.					
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002				
	Capacitance Change:					
	within ±2.5% or ±0.25pF whichever is larger					
	Q, IR: initial spec.					
Solderability	95% of the terminations is to be soldered	a) Preheat at 155°C for 4 hours, Immerse in solder for 5s at 245±5°C				
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C				
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C				
Floatrical	Compaitement Mithin an exist of television	solder: a solution ethanol and rosin				
Electrical	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25 ℃,				
Characterization	Q: 1000 max.	1Mt±10%, 0.5~5Vrms				
	IR(25°C): More than 100,000M Ω or 1,000M $\Omega \times \mu$ F IR(125°C): More than 10,000M Ω or 100M $\Omega \times \mu$ F	I.R. should be measured with a DC voltage not exceeding				
	Whichever is Smaller	Rated Voltage @25°C, @125°C for 60~120 sec. Dielectric Strength: 250% of the rated voltage for 1~5 seconds				
	Dielectric Strength	Dielectric Strength : 230 % of the rated voltage for 143 seconds				
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit (3mm) for 5 seconds				
Doura i lox	Capacitance Change:	Bonding to the mint (Omin) for a accorda				
	within ±5.0% or ±0.5pF whichever is larger					
Terminal	Appearance : No abnormal exterior appearance	10N, for 60±1 sec.				
Strength(SMD)	Capacitance Change :	1 , 1 32. 33.				
	within ±2.5% or ±0.25pF whichever is larger					
Beam Load	Destruction value should not be exceed	Beam speed				
	Chip Length < 2.5mm	0.5±0.05mm/sec				
	a) Chip Thickness > 0.5mm : 20N					
	b) Chip Thickness ≤ 0.5mm : 8N					
Temperature	COG	1				
Characteristics		be within ±30PPM/°C)				
Characteristics	(From -55℃ to 125℃, Capacitance change should	be within ±30PPM/°C)				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\mathrm{C}$, 10sec. Max)

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.